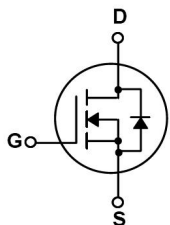


/ Descriptions

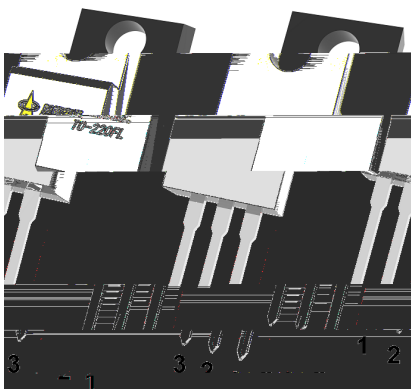
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



/ Marking

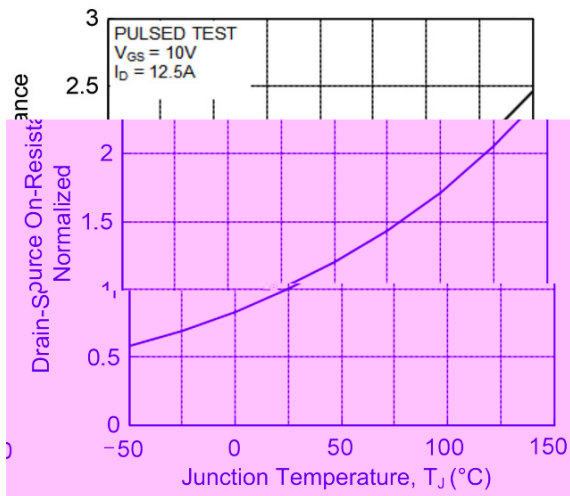
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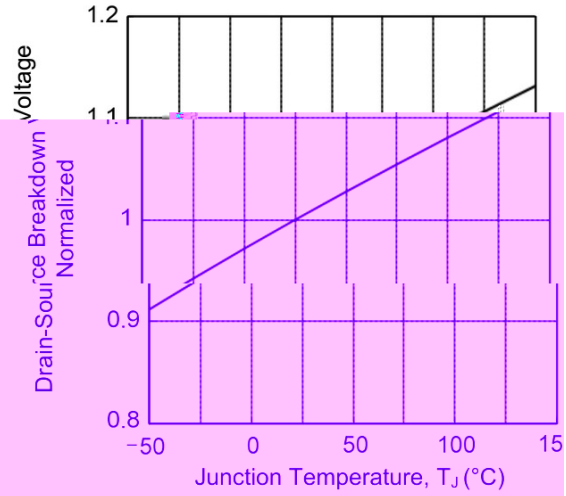
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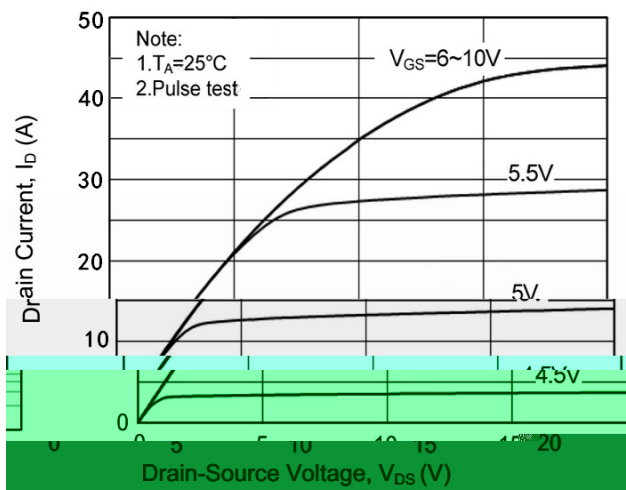
/ Electrical Characteristic Curve



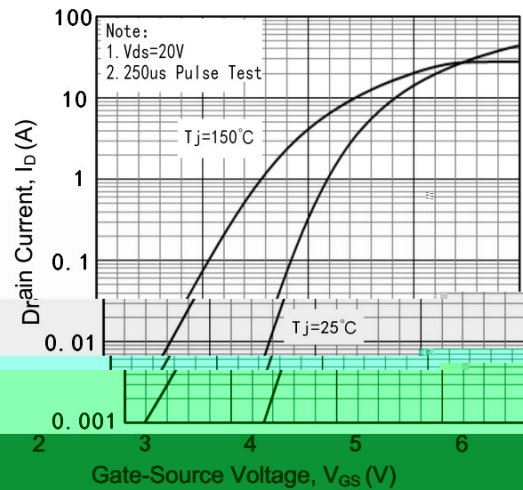
1. Drain-Source On-Resistance vs. Junction Temperature



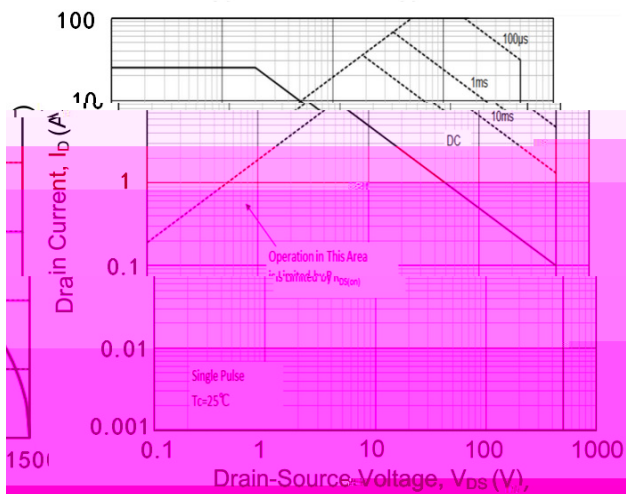
2. Breakdown Voltage vs. Junction Temperature



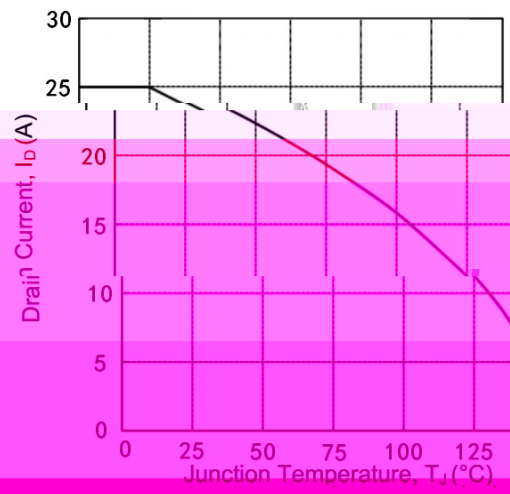
3. Drain Current vs. Drain-Source Voltage



4. Drain Current vs. Gate-Source Voltage

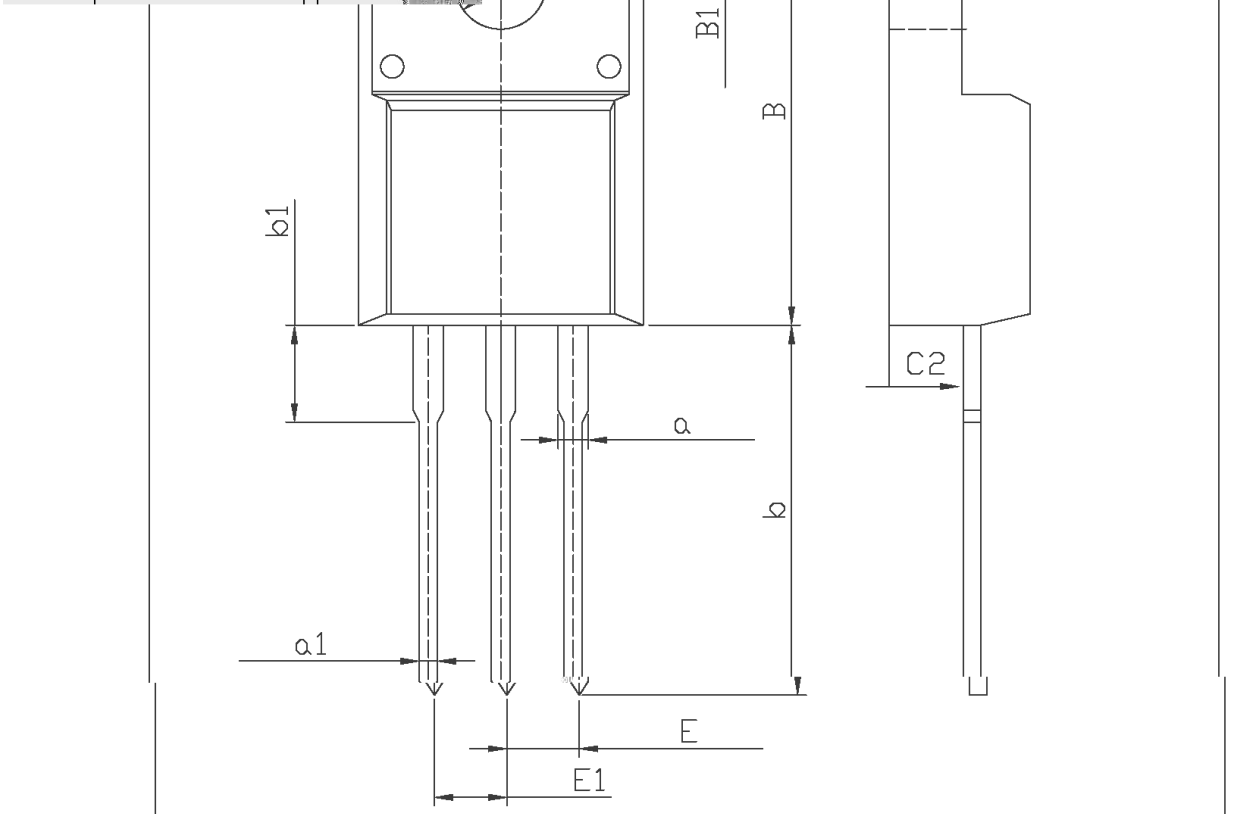
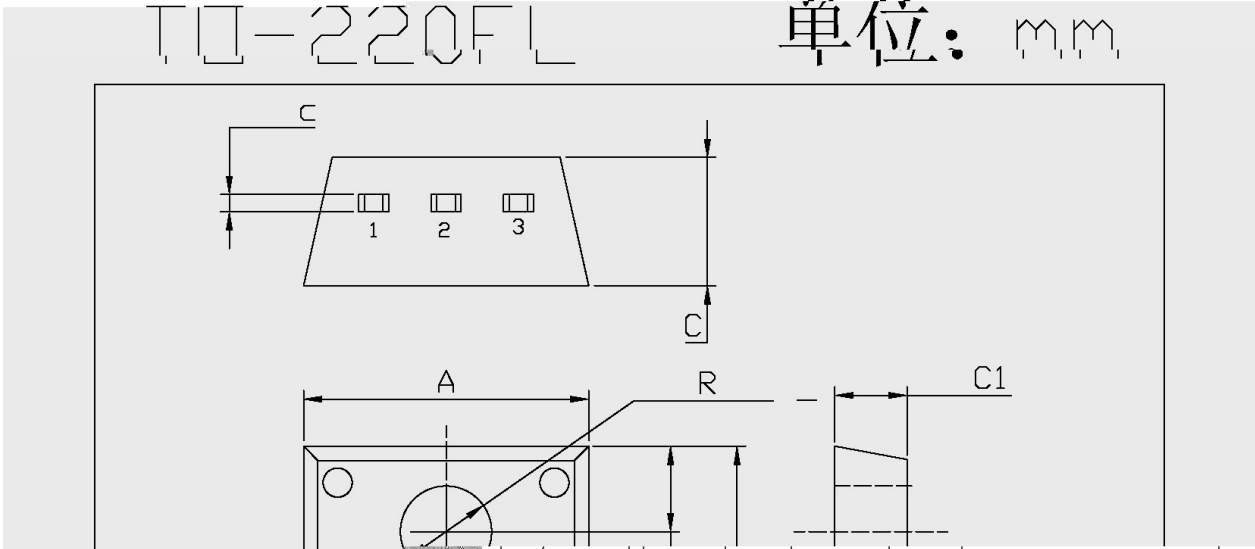


5. Safe Operating Area



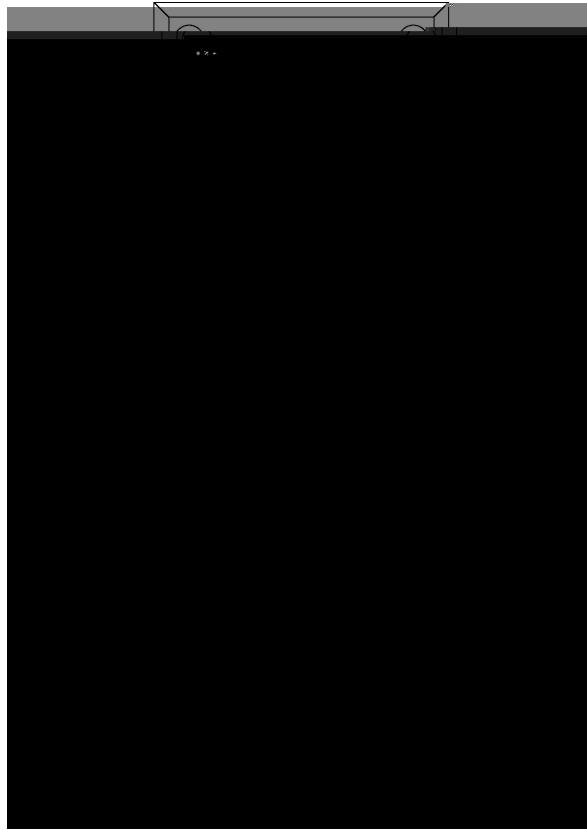
6. Drain Current vs. Junction Temperature

/ Package Dimensions



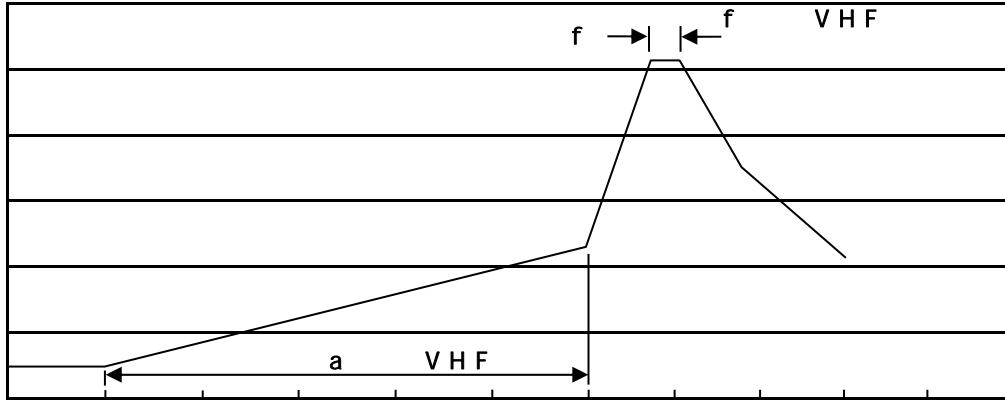
Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.5	4.7	b1	2.02	3.90
C	0.4	0.6	a	1.08	1.48
A	9.50	10.50	a1	0.70	0.90
B	15.67	16.07	E	2.34	2.74
B1	3.30	3.50	E1	2.34	2.74
R	3.08	3.28	C1	2.34	2.74

/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)

7 H P S H U D D W X U H



7 L P H V H F

/ Resistance to Soldering Heat Test Conditions

°C

/ Packaging SPEC.

7>û ~ E	;>û iH					;>û p . Æ		
	Units/Tube /•1x	Tubes/Inner Box •1x/-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Tube•1x	Inner Box	Outer Boxç

/ Notices